

**AMENDMENT TO THE ABSTRACT**

Please amend the Abstract as follows:

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An integrated circuit die comprising functional circuitry, a plurality of bond pads, each bond pad associated with a respective portion of the functional circuitry and for bonding the respective portion of the functional circuitry, at least one probe pad for testing of the functional circuitry; and multiplexing circuitry between the probe pad and the bond pads, the multiplexing circuitry for multiplexing signals between the probe pad and each of the respective portions of the functional circuitry, thus allowing the respective portions of functional circuitry to be tested using the probe pad and without any contact of the plurality of bond pads by a probe needle.